



DCR3030V42

Replaces DS5810-5

Phase Control Thyristor

DS5810-6	October 2023	(LN42860)
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FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages Vdrm and Vrrm (V)	Conditions
		$T_{vj} = -40^{\circ}C$ to $125^{\circ}C$,
DCR3030V42	4200	ldrm = Irrm = 200mA,
DCR3030V40	4000	Vdrm, Vrrm tp = 10ms
DCR3030V35	3500	Vdsm & Vrsm =
DCR3030V30	3000	Vdrm & Vrrm + 100V
		respectively

Lower voltage grades available.

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

DCR3030V42

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

Vdrm	4200V
Ιτ(Αν)	3020A
Тѕм	40600A
dV/dt*	1500V/µs
dl/dt	400A/µs

KEY PARAMETERS

* Higher dV/dt selections are available on request

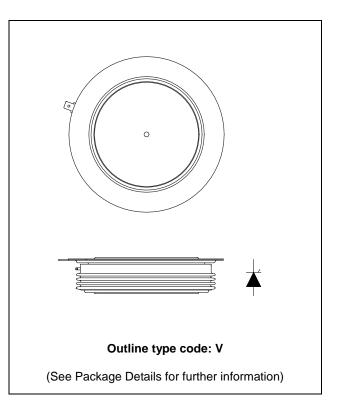


Fig. 1 Package outline

CURRENT RATINGS

T_{case} = 60°C unless stated otherwise

Symbol	Parameter Test Conditions		Max.	Units
Double Si	de Cooled			
Ιτ(Αν)	Mean on-state current	Half wave resistive load	3020	А
It(rms)	RMS value	-	4740	А
lτ	Continuous (direct) on-state current	-	4530	А

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SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
Ітѕм	Surge (non-repetitive) on-state current	10ms half sine, Tcase = 125°C	40.6	kA
l²t	I ² t for fusing	VR = 0	8.24	MA ² s

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditior	Test Conditions		Max.	Units
		Double side cooled	DC	-	7.5	°C/kW
Rth(j-c)	Rth(j-c) Thermal resistance - junction to case		Anode DC	-	13.0	°C/kW
		Single side cooled	Cathode DC	-	17.8	°C/kW
		Clamping force 54kN (with mounting compound)	Double side	-	2.0	°C/kW
Ktn(c-n)	Rth(c-h) Thermal resistance - case to heatsink		Single side	-	4.0	°C/kW
Tvj	Virtual junction temperature	Blocking VDRM / VRRM		-	125	°C
Tstg	Storage temperature range			-55	125	°C
Fm	Clamping force			48	59	kN

DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Condition	IS	Min.	Max.	Units
Irrm/Idrm	Peak reverse and off-state current	At VRRM/VDRM, Tcase = 125°C	,	-	200	mA
Vтм	Instantaneous forward voltage	At 4000A peak, Tj = 125°C		1.55	1.80	V
dV/dt	Max. linear rate of rise of off-state voltage	То 67% Vdrm, Тј = 125°С, ga	ate open	-	1500	V/µs
dl/dt	Rate of rise of on-state current	From 67% VDRM to 2x $I_{T(AV)}$ Gate source 30V, 10 Ω	Repetitive 50Hz	-	200	A/µs
ai/at		$tr < 0.5 \mu s, T_j = 125^{\circ}C$	Non-repetitive	-	400	A/µs
Veren	Threshold voltage - Low level	500A to 1800A at Tcase = 125°C		-	0.82	V
V τ(το)	Threshold voltage - High level	1800A to 7000A at T _{case} = 125°C		-	1.00	V
_	On-state slope resistance - Low level	500A to 1800A at T _{case} = 125°C		-	0.30	mΩ
ľτ	On-state slope resistance - High level	1800A to 7000A at T _{case} = 125°C		-	0.20	mΩ
tgd	Delay time	$V_D = 67\% V_{DRM}$, gate source 30V, 10 Ω tr = 0.5µs, Tj = 25°C		-	3	μs
tq	Turn-off time	$T_{j} = 125^{\circ}C, V_{R} = 200V, dI/dt = 1A/\mu s,$ $dV_{DR}/dt = 20V/\mu s \text{ linear}$		250	500	μs
Qs	Stored charge	Tj = 125°C, dl/dt = 1A/µs		1360	3400	μC
Irr	Reverse recovery current	Vr(peak) ~ 2500V, Vrм ~ 1700V		30	48	А
lı.	Latching current	$T_j = 25^{\circ}C, V_D = 5V$		-	3	А
Ін	Holding current	Тј = 25°С, Rg-к = ∞, Iтм = 50	0A, I⊤ = 5A	-	300	mA

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GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
Vgt	Gate trigger voltage	Vdrm = 5V, Tcase = 25°C	1.5	V
Vgd	Gate non-trigger voltage	At 50% Vdrm, Tcase = 125°C	0.4	V
Іст	Gate trigger current	Vdrm = 5V, Tcase = 25°C	350	mA
Igd	Gate non-trigger current	At 50% Vdrm, Tcase = 125°C	10	mA

CURVES

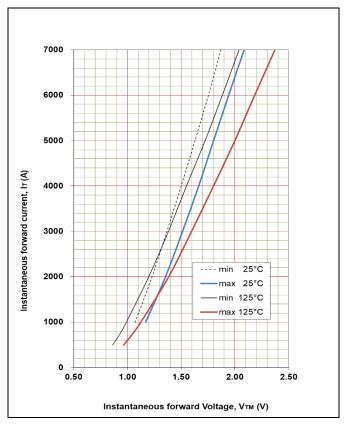


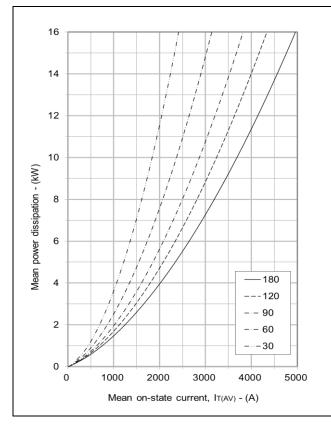
Fig. 2 Maximum & minimum on state characteristics

VTM EQUATION

$$V_{TM} = A + B.ln(I_T) + C.I_T + D.\sqrt{I_T}$$

Where A = 0.865481B = -0.041628C = 0.000099D = 0.014074These values are valid for T_j = 125° C for I_T 500A to 7000A

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Fig. 3 On-state power dissipation - sine wave

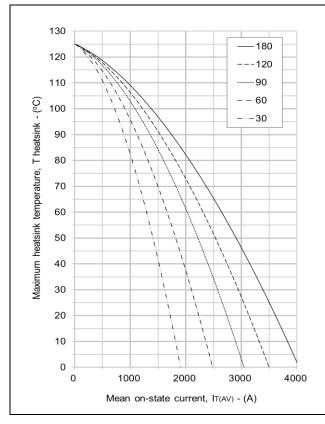


Fig. 5 Maximum permissible heatsink temperature, double side cooled - sine wave

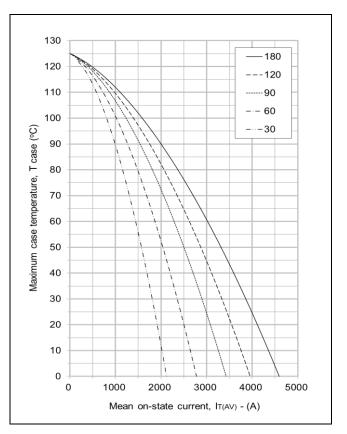


Fig. 4 Maximum permissible case temperature, double side cooled - sine wave

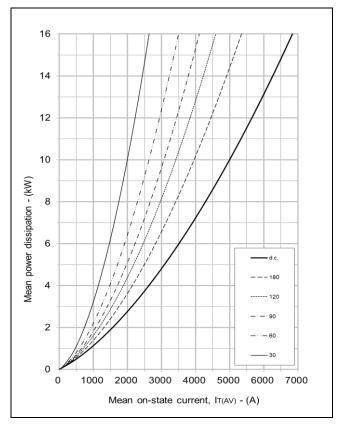


Fig. 6 On-state power dissipation - rectangular wave

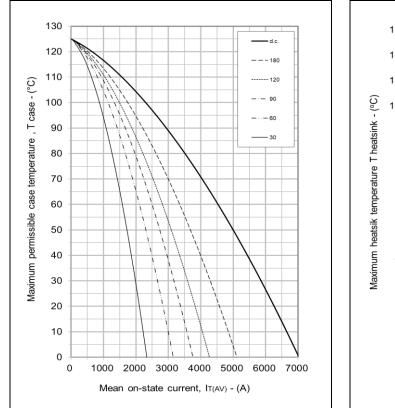
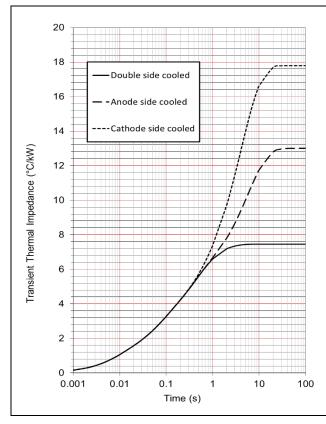


Fig. 7 Maximum permissible case temperature, double side cooled - rectangular wave



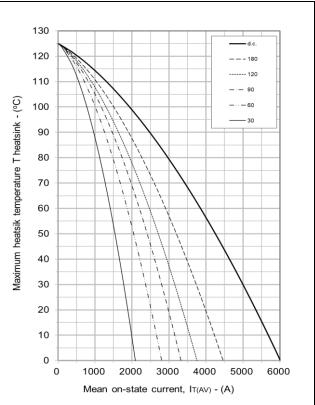


Fig. 8 Maximum permissible heatsink temperature, double side cooled - rectangular wave

		1	2	3	4
Double side	Ri(°C/kW)	0.921	1.830	3.402	1.304
cooled	Ti(s)	0.008	0.058	0.408	1.209
Anode side	Ri(°C/kW)	0.903	1.672	3.010	7.427
cooled	Ti(s)	0.008	0.054	0.314	5.624
Cathode side	Ri(°C/kW)	0.948	2.066	1.688	13.085
cooled	Ti(s)	0.008	0.065	0.389	4.145

$$Z_{th} = \sum_{i=1}^{i=4} R_i \cdot \left(1 - \exp\left(-\frac{T}{T_i}\right)\right)$$

∆R_{th(j-c)} Conduction

Tables show the increments of thermal resistance R $_{\text{fr}(j-q)}$ when the device operates at conduction angles other than d.c.

	Double side co	le side cooling		Anode Side Cooling		Ca	Cathode Sided Cooling		
	ΔZ _{th} (Z)		ΔZ	_{th} (Z)		ΔZ	h (Z)	
θ°	sine.	rect.	θ°	sine.	rect.	θ°	sine.	rect.	
180	1.34	0.88	180	1.34	0.88	180	1.33	0.88	
120	1.57	1.30	120	1.57	1.30	120	1.57	1 29	
90	1.83	1.54	90	1 84	1.54	90	183	1.53	
60	2.08	1.81	60	2.08	1.81	60	2.07	1.80	
30	2.27	2.11	30	2.28	2.11	30	2.26	2.10	
15	2.36	2.28	15	2.37	2.28	15	2.35	2.26	

Fig. 9 Maximum (limit) transient thermal impedance - junction to case (degC/kW)

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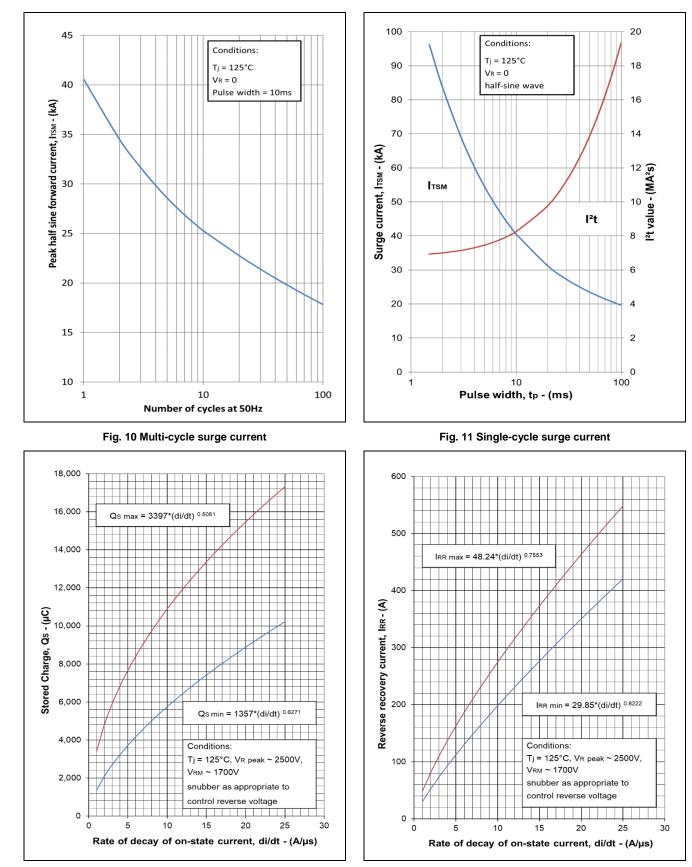
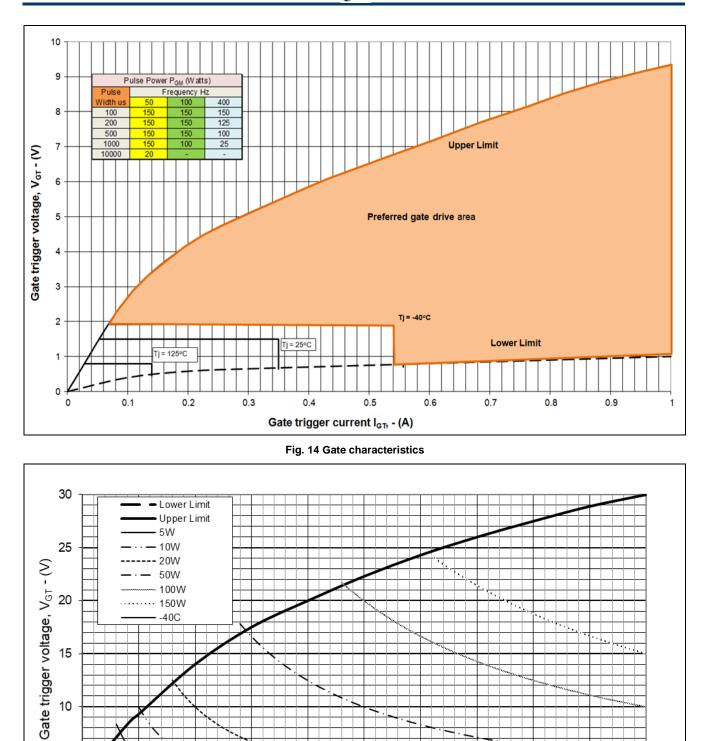


Fig. 12 Stored charge

Fig. 13 Reverse recovery current



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Gate trigger current, I_{GT} - (A)

Fig. 15 Gate characteristics

PACKAGE DETAILS

For further package information, please contact Customer services.

All dimensions in mm, unless stated otherwise.

DO NOT SCALE

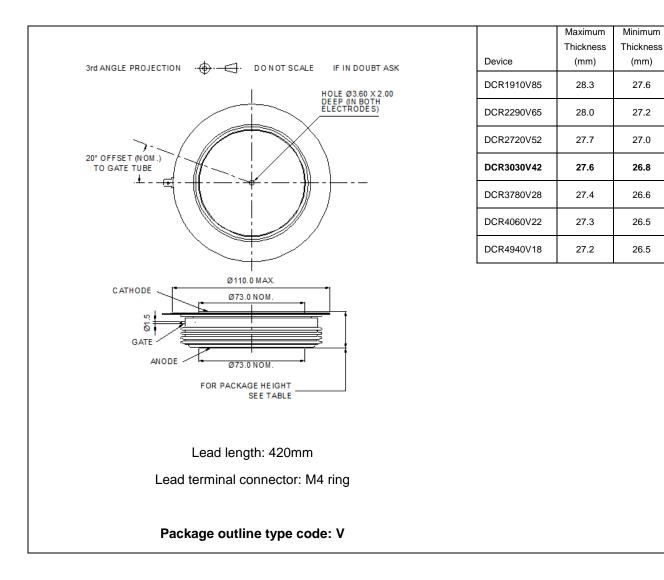


Fig. 16 Package outline

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